

N-Channel Enhancement Mode MOSFET

General Description

The 55N10 uses advanced trench technology to provide excellent $R_{DS(ON)}$, device is suitable for use as a Battery protection or in other Switching application.

Application

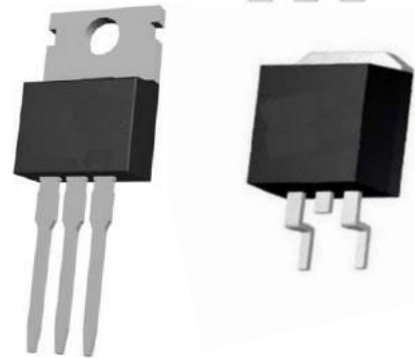
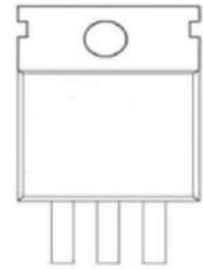
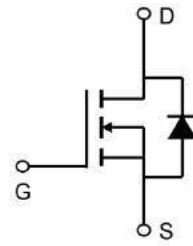
Battery protection Load switch

Uninterruptible power supply

General Features

$V_{DS} = 100V$ $I_D = 55A$

$R_{DS(ON)} < 21m\Omega @ V_{GS}=10V$



Absolute Maximum Ratings at $T_j=25^\circ C$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_{DS}	Drain source voltage	100	V
V_{GS}	Gate source voltage	± 20	V
I_D	Continuous drain current ¹⁾ , $T_C=25^\circ C$	55	A
$I_{D, pulse}$	Pulsed drain current ²⁾ , $T_C=25^\circ C$	110	A
P_D	Power dissipation ³⁾ , $T_C=25^\circ C$	50	W
E_{AS}	Single pulsed avalanche energy ⁵⁾	57	mJ
T_{stg}, T_j	Operation and storage temperature	-55 to 150	$^\circ C$

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Electrical Characteristics at $T_j=25\text{ }^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
BVDSS	Drain-source breakdown voltage	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	100			V
VGS(th)	Gate threshold voltage	$V_{DS}=V_{GS}, I_D=250\text{ }\mu\text{A}$	1.4		2.5	V
RDS(ON)	Drain-source on-state resistance	$V_{GS}=10\text{ V}, I_D=10\text{ A}$		15	21	m Ω
RDS(ON)	Drain-source on-state resistance	$V_{GS}=4.5\text{ V}, I_D=7\text{ A}$		20	26	m Ω
IGSS	Gate-source leakage current	$V_{GS}=20\text{ V}$			100	nA
		$V_{GS}=-20\text{ V}$			-100	
IDSS	Drain-source leakage current	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}$			1	μA
Ciss	Input capacitance	$V_{GS}=0\text{ V}, V_{DS}=50\text{ V},$ $f=100\text{ kHz}$		1003.9		pF
Coss	Output capacitance			185.4		pF
Crss	Reverse transfer capacitance			9.8		pF
td(on)	Turn-on delay time	$V_{GS}=10\text{ V},$ $V_{DS}=50\text{ V},$ $R_G=10\text{ }\Omega,$ $I_D=5\text{ A}$		16.6		ns
t_r	Rise time			3.8		ns
td(off)	Turn-off delay time			75.5		ns
t_f	Fall time			46		ns
Q_g	Total gate charge	$I_D=5\text{ A},$ $V_{DS}=50\text{ V},$ $V_{GS}=10\text{ V}$		16.2		nC
Q_{gs}	Gate-source charge			2.8		nC
Q_{gd}	Gate-drain charge			4.1		nC
Vplateau	Gate plateau voltage			3		V
I_S	Diode forward current				16	A
ISP	Pulsed source current	$V_{GS}<V_{th}$			48	
VSD	Diode forward voltage	$I_S=1234\text{ A}, V_{GS}=0\text{ V}$			1.3	V
trr	Reverse recovery time	$I_S=5\text{ A}, di/dt=100$ $\text{A}/\mu\text{s}$		49		ns
Q_{rr}	Reverse recovery charge			61.8		nC
Irrm	Peak reverse recovery current			2.4		A

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=50\text{ V}, R_G=50\text{ }\Omega, L=0.3\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

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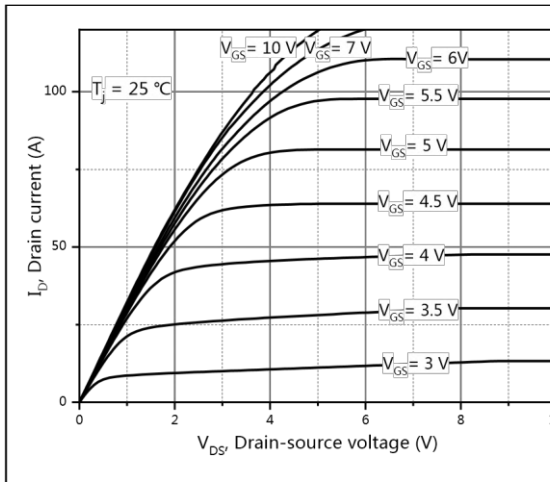


Figure 1, Typ. output characteristics

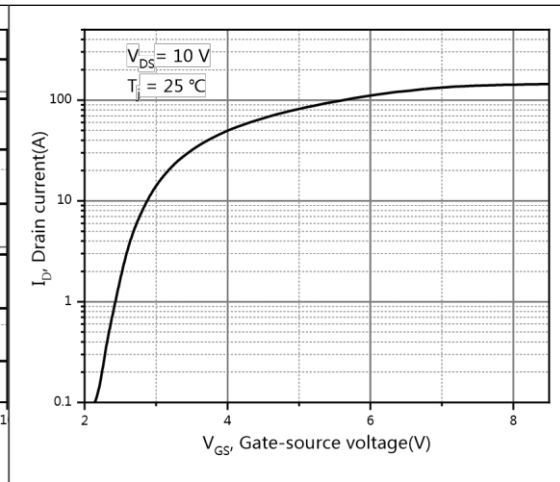


Figure 2, Typ. transfer characteristics

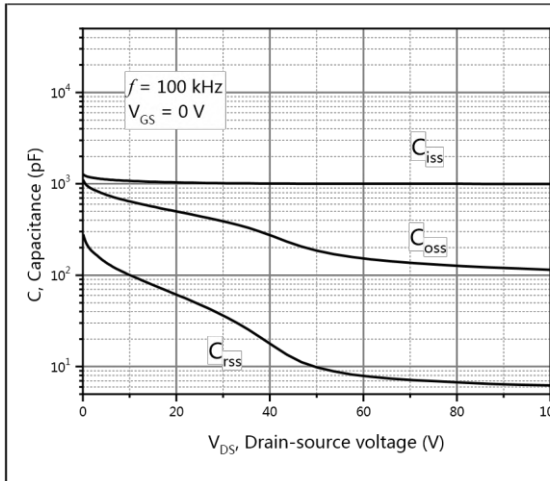


Figure 3, Typ. capacitances

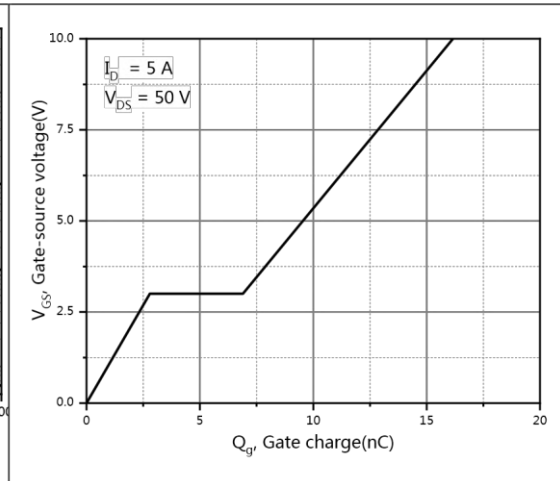


Figure 4, Typ. gate charge

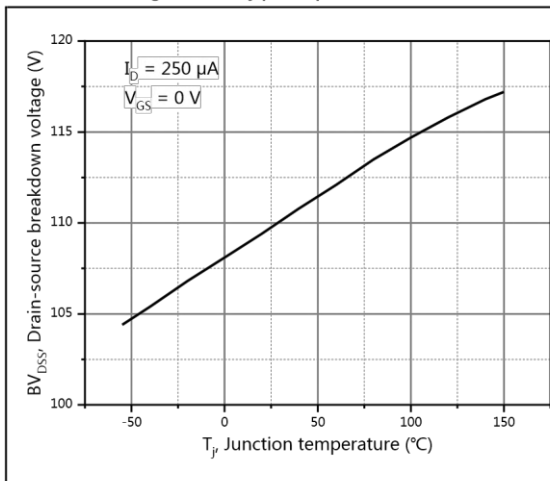


Figure 5, Drain-source breakdown voltage

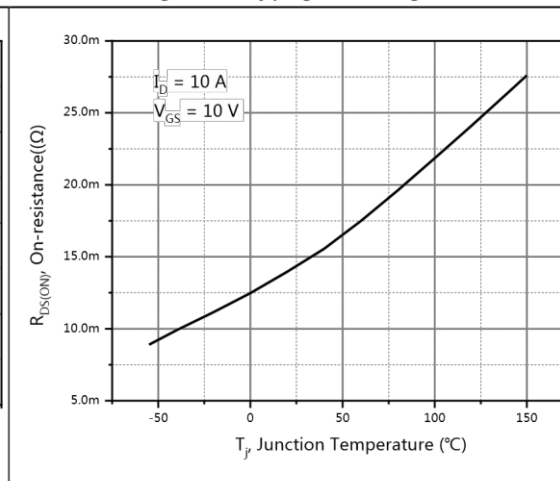


Figure 6, Drain-source on-state resistance

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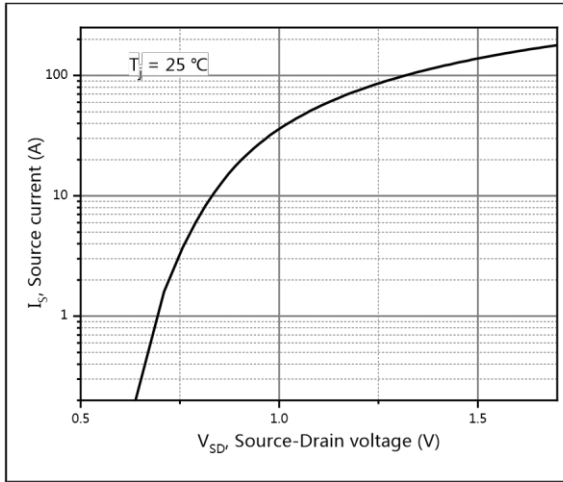


Figure 7, Forward characteristic of body diode

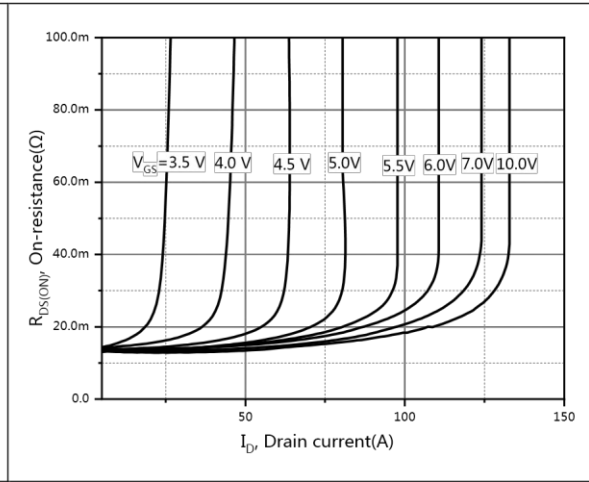


Figure 8, Drain-source on-state resistance

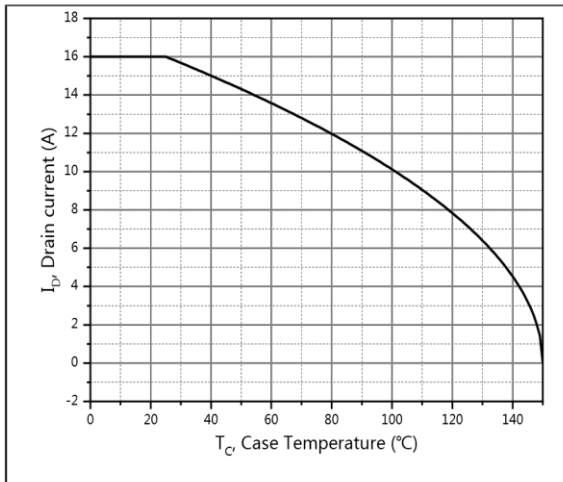


Figure 9, Drain current

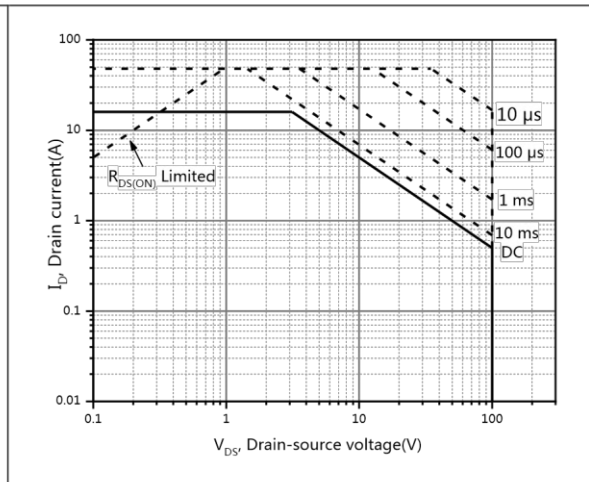


Figure 10, Safe operation area $T_C=25\text{ }^\circ\text{C}$

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